

## Programmable power line communication modem System on Chip

Datasheet - production data



### Features

- Programmable power line communication (PLC) modem System on Chip
- Integrated differential PLC analog front-end
  - PGA with automatic gain control and ADC
  - DAC with transmission pre-driver
  - Digital transmission level control
  - Zero crossing comparator
  - Up to 500 kHz PLC signal bandwidth
- High performance, fully programmable real-time engine dedicated to PLC PHY and real-time MAC protocol management (400 MHz max. frequency)
  - Dedicated code and data SRAM memories
- Standard ARM® 32-bit Cortex®-M4F fully programmable core for protocol upper layers and peripherals management
  - 200 MHz maximum frequency
  - 256 kB of embedded SRAM for code and data
  - 96 kB of embedded SRAM for data
  - 8 kB of embedded shared RAM
  - Bootloader ROM memory
  - One Time Programmable (OTP) memory with dedicated areas available for secure keys and user information storage
  - Serial wire and JTAG interfaces
  - 24 multiplexed GPIOs
  - 4 general purpose timers

- 1 flexible CRC calculation unit
- 2 USART, 1 UART, 3 SPI, 1 I<sup>2</sup>C
- Cryptographic engine
  - AES 128/192/256 engine
  - True random number generator
  - Pseudo random number generator
- Clock management:
  - 25 MHz external crystal for system clock
  - Integrated 25 MHz oscillator (XOSC) with frequency synthesizer (FS) and pre-scaler units to generate internal clock signals
- Power management
  - 3.3 V external supply voltage for I/O and analog
  - 2.5 V internal linear regulator for analog
  - 1.1 V external supply voltage for digital
  - Normal, Slow, Doze and low power modes
- Available in QFN56 package
- -40 °C to +105 °C temperature range

### Applications

- Smart metering, smart grid and Internet of Things applications
- Suitable for application design compliant with CENELEC, FCC and ARIB regulations

**Table 1. Device summary**

Order code	Package	Packing
ST8500	QFN56	Tray
ST8500TR		Tape and reel

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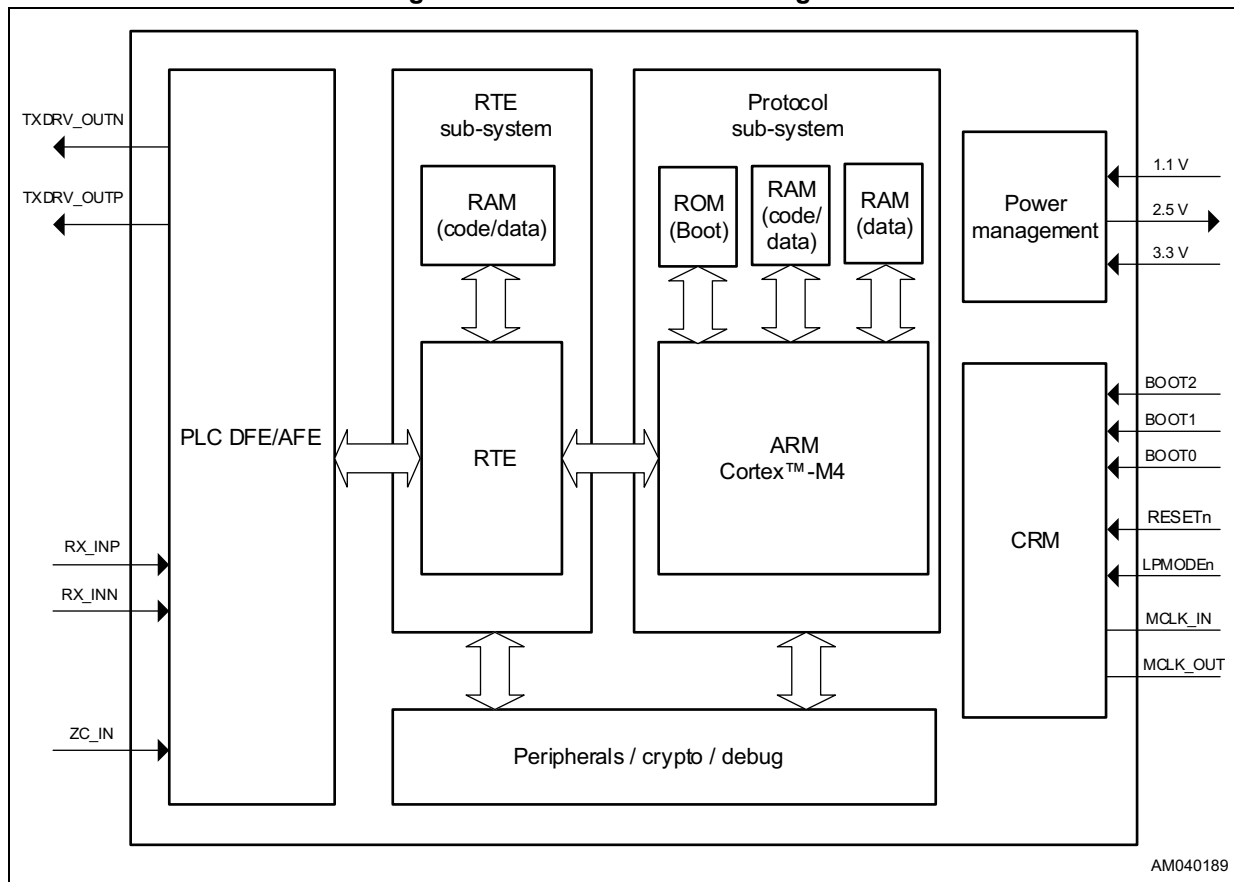
# 1 Description

The ST8500 is a fully programmable power line communication (PLC) modem System on Chip (SoC), able to run any PLC protocol in the frequency band up to 500 kHz.

The device architecture has been designed to target CENELEC EN50065, FCC and ARIB compliant applications supporting all major PLC protocol standards such as ITU G.9904 (PRIME), ITU G.9903 (G3-PLC<sup>®</sup>) and many other possible PLC protocol specifications and evolutions.

The ST8500 basic block diagram is shown in [Figure 1](#).

**Figure 1. ST8500 basic block diagram**



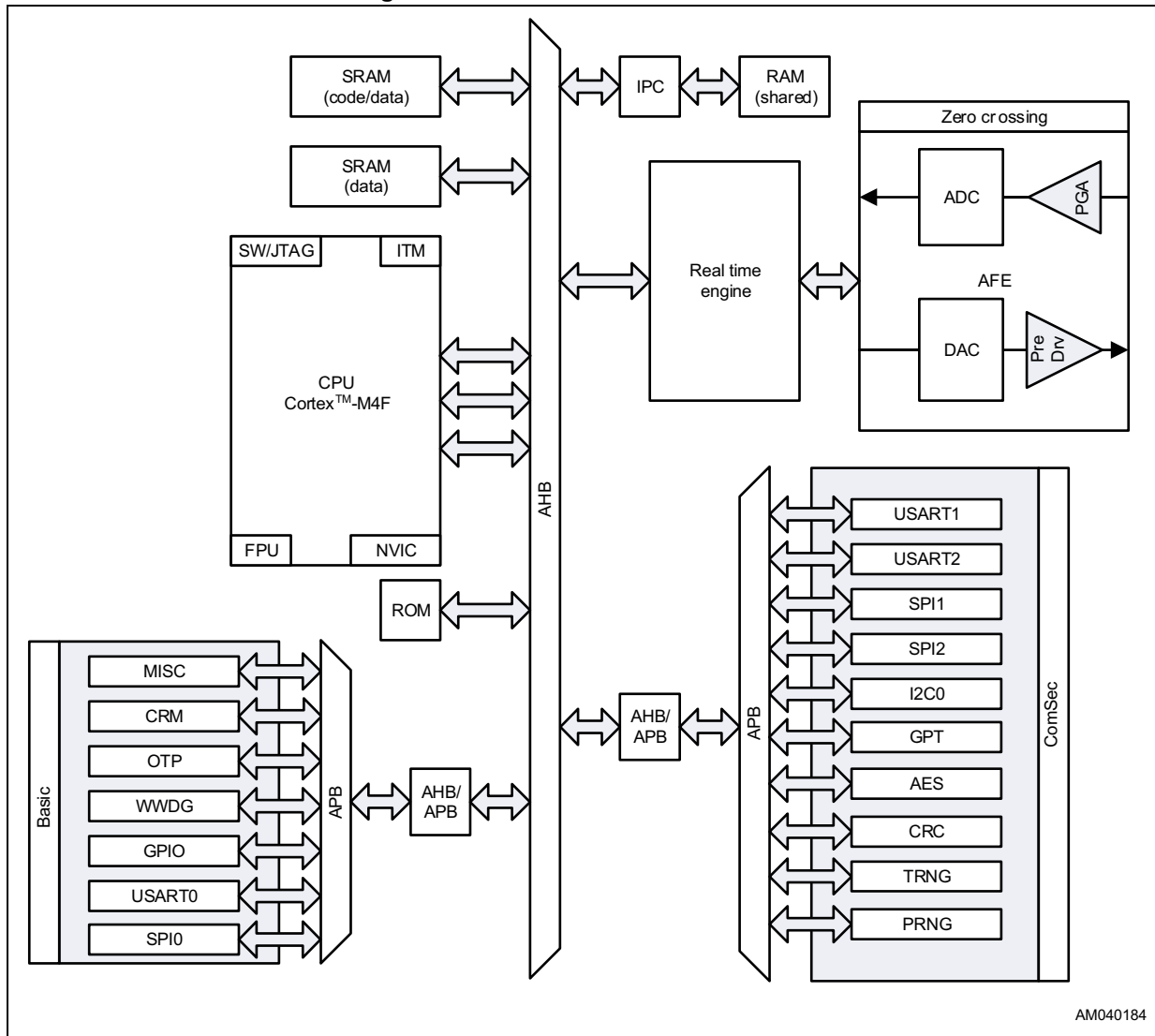
## 2 Device architecture

The ST8500 architecture is composed of the following parts:

1. PLC front-end including digital front-end (DFE) and analog front-end (AFE)
2. Real-time engine: the digital core running the lower layers of the PLC protocol stack and implementing modulation, demodulation and advanced forward error corrections (FEC) algorithms
3. Protocol engine: the digital core running the upper layers of the PLC protocol stack and managing the interface with external microcontrollers.
4. Peripherals, crypto, debug section
5. Clock and reset section
6. Power management section

The ST8500 detailed architecture is shown in [Figure 2](#).

Figure 2. ST8500 detailed architecture



## 2.1 Power line communication (PLC) subsystem

The ST8500 device embeds a fully programmable power line communication subsystem, comprising the RTE, DFE and AFE.

The AFE has been designed for a differential power line interface; however, the single-ended operation is possible for simpler hardware application development.

The DC to 500 kHz signal bandwidth is supported, targeting a number of possible PLC solutions.

## 2.1.1 Digital front-end (DFE)

### Transmission and reception filter chains

The DFE includes programmable transmission/reception digital filter chains to fit the signal bandwidth in different PLC modulation cases. The ADC and DAC clock frequencies are controlled by the DFE to get the right sample rate fitting the filter chain configuration.

### Automatic gain control (AGC)

The DFE implements the automatic gain control (AGC) block for the PGA, whose purpose is to adapt the signal to the ADC dynamic range.

## 2.1.2 Analog front-end (AFE)

### Reception chain

The ST8500 AFE features a programmable gain amplifier (PGA) and a dedicated analog-to-digital converter (ADC) to achieve high RX sensitivity and a wide input range.

### Transmission chain

The transmitted signal, generated in the digital domain, is fed into a dedicated digital-to-analog converter (DAC).

The DAC output is then fed into a pre-driver for buffering and applying an additional gain.

### Zero crossing comparator

The mains line zero crossing can be detected by providing a mains synchronous bipolar (AC) signal at the input of this comparator.

The zero crossing comparator provides positive and negative event information (rising/falling edge or high/low level).

Zero crossing information can also trigger an event for the GPT0 timer in order to capture the zero crossing timestamp for the application purpose.

### Line driver thermal sense

The AFE also includes the thermal sense (TS) block to detect the temperature of the line driver.

### Line driver current sense

The AFE also includes the current sense (CS) block to detect the output current of the line driver.

## 2.1.3 Real-time engine (RTE)

To effectively and flexibly target the performance required by different PLC standards, the ST8500 embeds a dedicated high performance fully programmable real-time engine (RTE). It is able to address specific real-time PLC functionalities such as modulation and demodulation according to different modulation schemes, advanced correction coding algorithms (Viterbi, Convolutional, Reed-Solomon, etc.) and several other time-constrained communication services.

## 2.2 Protocol core subsystem

### 2.2.1 ARM<sup>®</sup> Cortex<sup>™</sup>-M4F core

The Cortex<sup>™</sup>-M4F processor is built on a high-performance processor core, with a 3-stage pipeline Harvard architecture, making it ideal for demanding embedded applications. The processor delivers exceptional power efficiency through an efficient instruction set and extensively optimized design, providing high end processing the hardware including IEEE754-compliant single precision (32-bit) floating point computation, a range of a single cycle and SIMD multiplication and multiply with accumulate capabilities, saturating arithmetic and dedicated hardware division.

To facilitate the design of cost-sensitive devices, the Cortex<sup>™</sup>-M4F processor implements tightly coupled system components that reduce the processor area while significantly improving interrupt handling and system debug capabilities. The Cortex<sup>™</sup>-M4F processor implements a version of the Thumb<sup>®</sup> instruction set based on the Thumb<sup>®</sup>-2 technology, ensuring high code density and reduced program memory requirements. The Cortex<sup>™</sup>-M4F instruction set provides the exceptional performance expected by a modern 32-bit architecture, with the high code density of 8-bit and 16-bit microcontrollers.

The Cortex<sup>™</sup>-M4F processor provides multiple interfaces using the AMBA<sup>™</sup> technology to provide high-speed, low latency memory accesses. It supports unaligned data accesses and implements atomic bit manipulation that enables faster peripheral controls, system spinlocks and thread-safe Boolean data handling.

**Table 2. Cortex<sup>™</sup>-M4F core configuration**

Component	Presence	Comment
MPU_PRESENT	No	Memory protection unit (MPU) is not present
NUM_IRQ	N/A	Number of interrupts: 32
LVL_WIDTH	N/A	Interrupt priority width: 3
DEBUG_LVL	N/A	Minimum debug. 2 breakpoints, 1 watchpoint, no Flash patch
JTAG	Yes	JTAG-DP is included. The SW-DP is always included.
ITM	Yes	Instrumentation Trace Macrocell <sup>™</sup>
DWT	Yes	Data watchpoint and trace
WIC	No	Wake-up interrupt controller (WIC) is not present
BB	No	Bit banding region is not present
FPU	Yes	Floating point unit present (single precision)

### 2.2.2 Multi-AHB bus matrix

The 32-bit multi-AHB bus matrix interconnects all the masters (Cortex<sup>™</sup>-M4F and RTE) and the slaves (RAM, AHB and APB peripherals and real-time engine) and ensures a seamless and efficient operation even when several high-speed peripherals work simultaneously.



### 2.2.3 Debug with serial wire JTAG debug port (SWJ-DP)

The ARM SWJ-DP interface is embedded, and is a combined JTAG and serial wire debug port that enables either a serial wire debug or a JTAG probe to be connected to the target.

### 2.2.4 Floating point unit (FPU)

The FPU fully supports single precision add, subtract, multiply, divide, multiply and accumulate, and square root operations. It also provides conversions between the fixed point and floating point data formats, and floating point constant instructions.

The FPU provides floating point operations that are compliant with the NSI/IEEE Std 754-2008 A, IEEE Standard for Binary Floating-point Arithmetic<sup>®</sup>, referred to as the IEEE 754 Standard.

The FPU contains 32 single precision extension registers, which can also be accessible as 16 double word registers for load, store, and move operations.

### 2.2.5 Nested vectored interrupt controller (NVIC)

The ST8500 embeds a NVIC closely integrated with the ARM Cortex™-M4F core. The NVIC is able to handle 32 maskable interrupts. The software priority level is configurable in the range of 0 - 31 for each interrupt. A higher level corresponds to a lower priority, so the level 0 is the highest interrupt priority. In case two or more interrupt lines share the same software priority level, the hardware priority level is used. Interrupt descriptions and hardware priorities are shown in [Table 3](#).

**Table 3. Interrupt definition and position**

Position	Hardware priority	Acronym	Description	Offset from VTOR
-	-3	Reset	Reset	0x00000004
-	-2	NMI	Non maskable interrupt - system error	0x00000008
-	-1	HardFault	All class of fault	0x0000000C
-	0	MemManage	MPU mismatch	0x00000010
-	1	BusFault	Prefetch fault, memory access fault	0x00000014
-	2	UsageFault	Undefined instruction or illegal state	0x00000018
-	-	-	Not present	0x0000001C
-	-	-	Not present	0x00000020
-	-	-	Not present	0x00000024
-	-	-	Not present	0x00000028
-	3	SVCall	System service call via SWI instruction	0x0000002C
-	4	Debug Monitor	Debug monitor	0x00000030
-	-	-	Not present	0x00000034
-	5	PendSV	Pendable request for system service	0x00000038
-	6	Systick	System tick timer	0x0000003C
0	7	lpmode_entry_irq	CRM low power mode enter interrupt	0x00000040
1	8	lpmode_exit_irq	CRM low power mode exit interrupt	0x00000044

**Table 3. Interrupt definition and position (continued)**

Position	Hardware priority	Acronym	Description	Offset from VTOR
2	9	crm_error_irq	CRM error interrupt	0x00000048
3	10	WWDG	Window watchdog - global interrupt	0x0000004C
4	11	GPT0	GPT0 - global interrupt	0x00000050
5	12	GPT1	GPT1 - global interrupt	0x00000054
6	13	GPT2	GPT2 - global interrupt	0x00000058
7	14	GPT3	GPT3 - global interrupt	0x0000005C
8	15	SPI0	SPI0 - global interrupt	0x00000060
9	16	SPI1	SPI1 - global interrupt	0x00000064
10	17	SPI2	SPI2 - global interrupt	0x00000068
11	18	USART0	USART0 - global interrupt	0x0000006C
12	19	USART1	USART1 - global interrupt	0x00000070
13	20	USART2	USART2 - global interrupt	0x00000074
14	21	IPC_mailbox	IPC - mailbox interrupt	0x00000078
15	22	IPC_queues	IPC - queues interrupt	0x0000007C
16	23	IPC_mem	IPC - shared memory Interrupt	0x00000080
17	24	I2C_event	I2C0 - global event interrupt	0x00000084
18	25	I2C_error	I2C0 - global error interrupt	0x00000088
19	26	AES	AES - global interrupt	0x0000008C
20	27	OTP_error	OTP - global error interrupt	0x00000090
21	28	OTP_eoo	OTP - end of operation interrupt	0x00000094
22	29	GPIO00	GPIO00 - global interrupt	0x00000098
23	30	GPIO01	GPIO01 - global interrupt	0x0000009C
24	31	-	Reserved	0x000000A0
25	32	GPIO03	GPIO03 - global interrupt	0x000000A4
26	33	-	Reserved	0x000000A8
27	34	-	Reserved	0x000000AC
28	35	-	Reserved	0x000000B0
29	36	FPU	Floating point unit - global interrupt	0x000000B4
30	37	-	Reserved	0x000000B8
31	38	-	Reserved	0x000000BC

## 2.2.6 General-purpose input/outputs (GPIOs)

The ST8500 device has 3 GPIOs ports named GPIO00, GPIO01 and GPIO03. Each port can control 8 pins. Each GPIO pin can be individually configured by software as output (push-pull or open drain, with or without pull-up or pull-down), as input (floating, with or without pull-up or pull-down) or as peripheral alternate functions (with or without pull-up or pull-down).

The GPIO03 port exports system defined functionalities such as boot mode selection and JTAG that the running code can overwrite after the bootloader has left the control to it. The final system design must take care of this special configuration.

### External interrupt

Each GPIOs port can generate interrupts depending on a level (low and high), or a transactional value of the pin (rising or falling edge). For each port, one interrupt line is dedicated. The pins of one port share the same interrupt line.

## 2.2.7 General-purpose timer (GPT)

There are 4 general-purpose timers (GPT0 to GPT3) embedded in the ST8500.

GPTs have a 32-bit auto-reload up/downcounter and a 32-bit pre-scaler. The counters can be frozen in debug mode.

The GPT0 timer is also connected to the zero crossing comparator so it is able to record the timestamp of the ZC event.

## 2.2.8 Window Watchdog (WWDG)

The window watchdog is based on a 7-bit downcounter that can be set as free running. It can be used as a watchdog to reset the device when a problem occurs. It is clocked from the main clock. It has an early warning interrupt capability and the counter can be frozen in debug mode.

## 2.2.9 SysTick timer

The Cortex™-M4F has a 24-bit system timer, SysTick, which counts down from the programmable reload value to zero. It supports the auto-reload and can generate a maskable system interrupt when the counter reaches zero.

## 2.2.10 Universal synchronous/asynchronous receiver transmitters (USART)

The ST8500 device has two embedded universal synchronous/asynchronous receiver transmitters (USART0 to USART1) and one embedded universal asynchronous receiver transmitter (USART2).

These interfaces provide asynchronous communication, IrDA SIR ENDEC support, multiprocessor communication mode, single-wire half-duplex communication mode; they have the LIN Master/Slave capability, Smart card mode (ISO 7816 compliant) and SPI-like communication capability.

They provide hardware management of the CTS and RTS signals and the RS485 driver enable. The maximum communication speed is up to 1 Mbit/s.

All USARTs have a clock domain (ICLK) independent from the Cortex™ clock (PCLK).

### 2.2.11 Serial peripheral interface (SPI)

Three SPI interfaces (SPI0 to SPI2) allow communication up to 50 Mbit/s in master and up to 24 Mbit/s slave modes, in half-duplex, full-duplex and simplex modes. The 3-bit pre-scaler gives 8 master mode frequencies and the frame size is configurable from 4 bits to 16 bits. The SPI interfaces support NSS pulse mode, TI mode and hardware CRC calculation.

### 2.2.12 Inter-integrated circuit interface (I<sup>2</sup>C)

The ST8500 device embeds one I<sup>2</sup>C. The I<sup>2</sup>C bus interface handles communications between the device and the serial I<sup>2</sup>C bus. It controls all I<sup>2</sup>C bus-specific sequencing, protocol, arbitration and timing. In addition to receiving and transmitting data, this interface converts it from the serial to the parallel format and vice versa. The interrupts are enabled or disabled by software. The interface is connected to the I<sup>2</sup>C bus by a data pin (SDA) and by a clock pin (SCL).

The I<sup>2</sup>C peripheral supports:

- I<sup>2</sup>C-bus specification and user manual rev. 5 compatibility:
  - Slave and master modes, multimaster capability
  - Standard-mode (Sm), with a bitrate up to 100 kbit/s
  - Fast-mode (Fm), with a bitrate up to 400 kbit/s
  - 7-bit and 10-bit addressing mode, multiple 7-bit slave addresses
  - Programmable setup and hold times
  - Optional clock stretching
- System management bus (SMBus) specification rev 2.0 compatibility:
  - Hardware PEC (packet error checking) generation and verification with ACK control
  - Address resolution protocol (ARP) support
  - SMBus alert
- Power System Management Protocol (PMBus™) specification rev 1.1 compatibility
- Independent clock (ICLK): a choice of independent clock sources allowing the I<sup>2</sup>C communication speed to be independent from the PCLK clock reprogramming.
- Programmable analog and digital noise filters

### 2.2.13 AES engine

The ST8500 embeds a hardware AES peripheral that implements an advanced standard cryptographic algorithm according to the NIST FIPS 197. The block processes 128-bit data blocks using a key with the following possible sizes: 128, 192, 256 bits. The peripheral also supports the following modes: “Electronic Code Book” (ECB), “Cipher Block Chaining” (CBC), “Counter mode” (CTR), “Galois/Counter Mode” (GCM), GMAC and CCM modes.

The peripheral is able to encrypt and decrypt data. Interrupt can be generated when one operation is finished.

### 2.2.14 True random number generator (TRNG)

The ST8500 embeds a TRNG processor based on a continuous analog noise that provides a random 16-bit value. To avoid pseudo random sequences, two consecutive accesses have to be performed when the ready bit in the status register is set to 1.

### 2.2.15 Pseudo random number generator (PRNG)

The ST8500 embeds a PRNG processor that provides a pseudo random 32-bit value. Initial seed can be configured by software.

### 2.2.16 CRC (cyclic redundancy check) calculation unit

The cyclic redundancy check (CRC) is a widely used method for detecting errors. The CRC calculation unit is used to get a CRC code in a flexible way using a configurable polynomial. The output data size can be selected between 8, 16, 24 or 32 bits.

The input data size can be configured between 1, 8, 16, 24 or 32 bits with selectable bit and byte endianness.

The CRC unit allows the specification of the initial value (all zero, all one, or a generic value) and the possibility to select an automatic XOR with all one when reading the data output.

## 2.3 Inter-processor communication (IPC)

The Cortex™-M4 core and the real-time engine (RTE) communicate by means of an additional 8-kByte shared static RAM. This memory can be accessed by the two cores through an interprocessor communication block that guarantees coherent and consistent read and modify operations, to provide several functionalities to the system, among the others:

- Configuration of real-time engine modes and functionalities during the normal working operations
- Data and information exchange between the Cortex™-M4 and real-time engine in both directions.

## 2.4 Cortex™ memories

### 2.4.1 Embedded SRAM (instruction and data)

The ST8500 device embeds 256 kByte of the SRAM for a fast code execution. This SRAM can be used also to store data with penalties in the concurrent instruction and data access. The data SRAM start address is 0x00050000, the end address is 0x0008FFFF.

### 2.4.2 Embedded SRAM (data only)

The ST8500 device embeds 96 kBytes of the SRAM for data management. The Cortex™-M4 can perform byte, half word (16 bits) or full word (32 bits) access to the SRAM at maximum speed, with zero wait states for both read and write operations. The data SRAM start address is 0x00090000, the end address is 0x000A7FFF.

### 2.4.3 Embedded ROM

The ST8500 device embeds a ROM memory used to store the bootloader program written during the device production phase.

### 2.4.4 One Time Programmable (OTP) section

The ST8500 device embeds an OTP area that stores device sensitive information, security control bits and additional user specific bytes. The OTP section has two different HW protection methods, ECC or HW redundancy, as indicated in [Table 4](#).

**Table 4. OTP section**

Word	Word size	Protection	Description
0	16 bits	HW redundancy	User security bits: b0: Cortex™-M4F images in clear text enabled b1: Cortex™-M4F JTAG enabled b2: user OTP write locked b3: Cortex™-M4F key read locked b4-15: reserved
1	32 bits	ECC	Cortex™-M4F image decryption key word0
2	32 bits	ECC	Cortex™-M4F image decryption key word1
3	32 bits	ECC	Cortex™-M4F image decryption key word2
4	32 bits	ECC	Cortex™-M4F image decryption key word3
5	32 bits	ECC	Cortex™-M4F image decryption key word4
6	32 bits	ECC	Cortex™-M4F image decryption key word5
7	32 bits	ECC	Cortex™-M4F image decryption key word6
8	32 bits	ECC	Cortex™-M4F image decryption key word7
9	32 bits	ECC	User specific word 0
10	32 bits	ECC	User specific word 1
11	32 bits	ECC	User specific word 2
12	32 bits	ECC	User specific word 3

The ECC calculation unit improves robustness of data storage. This ECC block encodes and decodes each 32-bits words in programming and reading operations. The user must program all the ECC protected words in one shot, no modification is possible afterward.

The HW redundancy is a more flexible protection mechanism but limits the size of each word to 16-bits. The user can write words in multiple shots but respecting this rule: the word value can be changed only making '0's becoming '1's (in no case single bits can be written back at 0).

## 2.5 Clock and reset management (CRM)

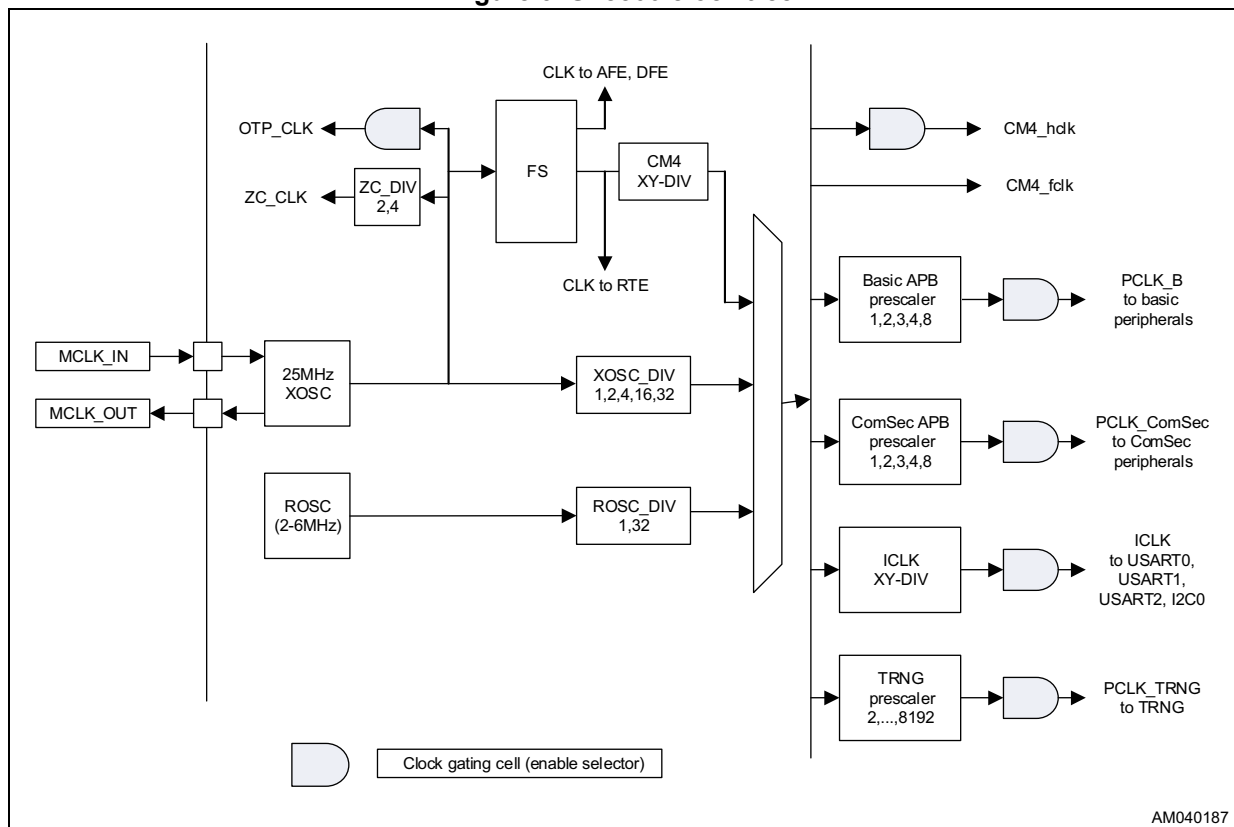
### 2.5.1 Clock management

ST8500 internal clock signals can be generated from two different clock sources:

1. An external 25 MHz that must be provided through a crystal connected to MCLK\_IN and MCLK\_OUT pins. If this source is not present the device does not start in order to respect the security requirements.
2. An internal ring oscillator with 4 MHz nominal frequency.

The clock strategy and distribution is depicted in [Figure 3](#).

**Figure 3. ST8500 clock tree**



At the power-on the Cortex™-M4F directly uses the XOSC clock with the SLOW mode. The internal frequency synthesizer (FS) and pre-scaler units generate all the needed internal clock signals. The frequency synthesizer generates a fixed frequency at a nominal frequency of 400 MHz (VCO). This frequency is pre-scaled at boot time to provide the proper clock for DFE, AFE and RTE subsystems.

The application code can select the clock source for the Cortex™-M4 subsystem between:

1. The VCO output of FS by means of a programmable pre-scaler. The application core must properly configure it to provide the clock in the range from 1.5 MHz to 200 MHz.
2. The 25 MHz oscillator by means of a programmable pre-scaler at a nominal frequency ranging from 0.8 MHz up to 25 MHz.
3. The internal ring oscillator, either directly (at a nominal frequency 4 MHz) or by means of a fixed pre-scaler (at a nominal frequency of 0.125 MHz).

Each APB bus can be fed at an integer fraction of the Cortex™-M4F clock with a prescaling factor up to 8. The application core must configure the APB clock to respect the maximum limit of 100 MHz. USART and I<sup>2</sup>C peripherals have an independent clock divider to generate the proper baudrate and clock on the line.

It is also possible to apply clock gating to each bus in case of low power mode or unused peripherals. Clock gating can be applied to clock signals as indicated in [Figure 3](#).

### 2.5.2 Reset management

The power-on-reset (POR) is conditioned by the level of the required supply voltages (3.3 V, 2.5 V and 1.1 V, see [Section 2.6](#)). At the power-on, the whole ST8500 is kept under reset until the supply voltages are above the respective turn-on thresholds, while the device is turned off as soon as one of the supply voltages fall below the respective turn-off thresholds.

The system reset is generated by:

- The RESETn pin (active low)
- The Cortex™-M4F core that can assert a system software reset
- The window watchdog (see [Section 2.2.8 on page 11](#))

The software reset to single peripherals can be forced through CRM registers.

## 2.6 Power management

The ST8500 shall be powered by at least two external supply voltages:

- 3.3 V for I/Os and TX driver
- 1.1 V for the digital part and memories

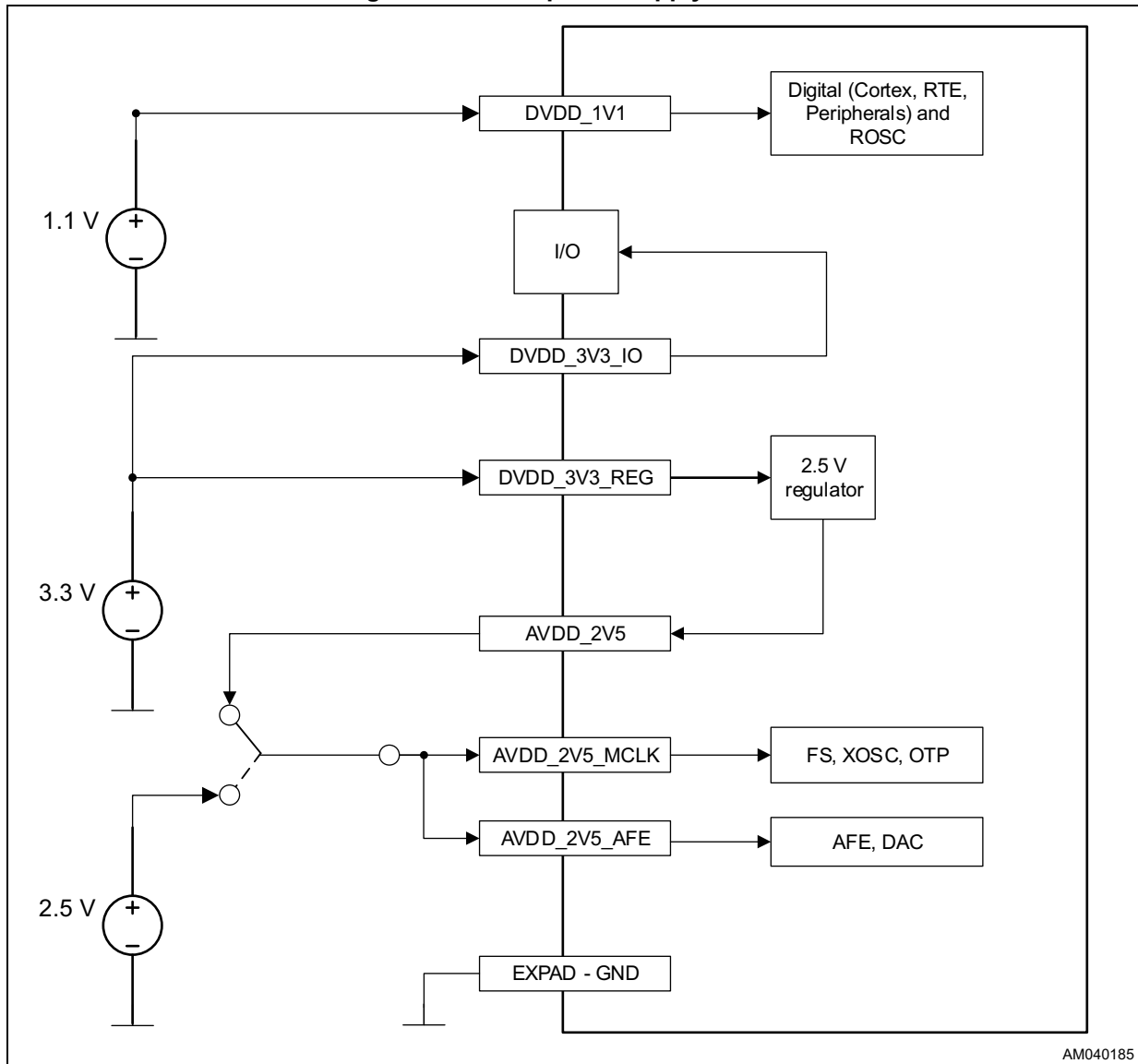
The device needs also an analog 2.5 V supply that can be either internally generated through an LDO from the 3.3 V supply, or externally supplied.

The internal regulator connected to AVDD\_2V5 is not designed to supply external circuitry; its output is externally accessible for filtering the purpose only.

The only ground reference of the device is the exposed pad (EXPAD-GND). It has to be properly soldered to a ground pad on the application PCB.



Figure 4. ST8500 power supply scheme



### 2.6.1 External power supply dimensioning

To cover all possible corner cases, the external power supply peak capability should take into account the values provided in [Table 5](#).

Table 5. Power supply peak consumption

Power supply rails	Conditions	Value	Unit
1.1 V supply rail	Full temperature range, maximum clock frequencies	420	mW
3.3 V supply rail		320	mW

## 2.6.2 System power modes and low-power mode

In order to fine-tune the power consumption, the ST8500 device supports different power modes. Based on the selected clock source (see [Section 2.5](#)) the Cortex™-M4 can select the system power mode between:

- NORMAL mode: the system is clocked by the VCO output frequency of the FS (with prescaling factor)
- SLOW mode: the system is clocked directly by the XOSC frequency
- DOZE mode: the system is clocked by the ROSC oscillator
- LOW-POWER mode: the system is clocked by the ROSC oscillator and additional power saving strategies can be applied.

In NORMAL mode, the Cortex™-M4 is able to run at its maximum frequency but, in case lower speed is sufficient to meet the application requirements, its clock frequency can be scaled down to reduce power consumption, while AFE, DFE and RTE frequencies are always internally selected to meet the running PLC protocol requirements. In case PLC connectivity is temporarily not required, the Cortex™-M4 can be put in SLOW (depending on the computational power and power consumption required) turning off the frequency synthesizer (and all the derived clock signals). When in DOZE mode also the XOSC block can be turned off.

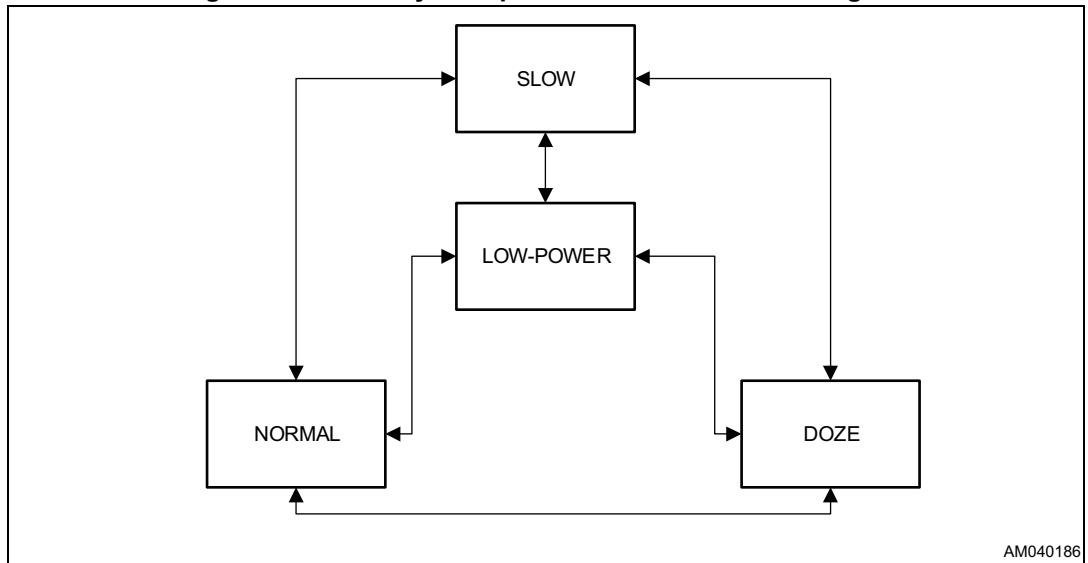
An additional LOW-POWER mode is present. In this mode it is possible to define which power reduction strategies are put in place by the means of a software selectable mask which can:

- Disable the AFE analog blocks
- Disable the external clock sources (XOSC and FS)
- Apply clock gating to all the digital blocks including the CPU
- Power down the SRAM memories

The LOW-POWER can be selected by the Cortex™-M4F or by an external controller with a dedicated pin (LPMODEn, active low). The exit from LOW-POWER mode is controlled by the Cortex™-M4, by LPMODEn pin, by internal GPT0 timer tick. During LOW-POWER mode the content of SRAM memories is still valid and accessible by cores if not put in power-down.

[Figure 5](#) shows the possible transitions between power system modes.

Figure 5. ST8500 system power modes transition diagram



AM040186

Clock gating is available in any modes for peripherals and clock sources in order to save all the dynamic power contributions related to the resources not used by the application.

## 2.7 Boot modes and system programmability

ST8500 boot mode is defined by the status of the three pins GPIO3\_0/BOOT0, GPIO3\_1/BOOT1, GPIO3\_2/BOOT2 when the device awakes from a reset condition (either power-on, hardware or software reset), the correspondence between the value of BOOTx pins and the boot mode is shown in [Table 6](#).

Table 6. Boot modes selection

Boot pins			Boot mode
BOOT2	BOOT1	BOOT0	
0	0	0	Boot from UART host interface
0	0	1	Boot from SPI host interface
0	1	0	Boot from SPI external Flash (large configuration)
0	1	1	Boot from SPI external Flash (small configuration)
1	0	0	Reserved1
1	0	1	Reserved1
1	1	0	Reserved1
1	1	1	Reserved2

The application and RTE codes can be either downloaded by the external host (through SPI or UART interface) or written as binary images on one external SPI Flash (either up to 4 Mbit for the small configuration or from 8 Mbit for the large configuration). The internal bootloader takes the responsibility to load the codes in the proper cores and to start running them. If “Reserved2” mode is selected an endless loop is performed. If one of the

“Reserved1” modes is selected the bootloader automatically jumps to the RAM code starting address. In this case, the user can access to the device through the JTAG if not locked.

The system JTAG is not accessible during the execution of the bootloader procedure. At the end of the bootloader, it becomes accessible. It is also possible by means of an appropriate user security bit in the OTP memory (see [Section 2.4.4 on page 14](#)), to keep the JTAG port locked even after the boot procedure, to avoid unwanted accesses to the core and memories.

### 3 Pinout and pin description

#### 3.1 Pin definition

Figure 6. ST8500 QFN56 pinout

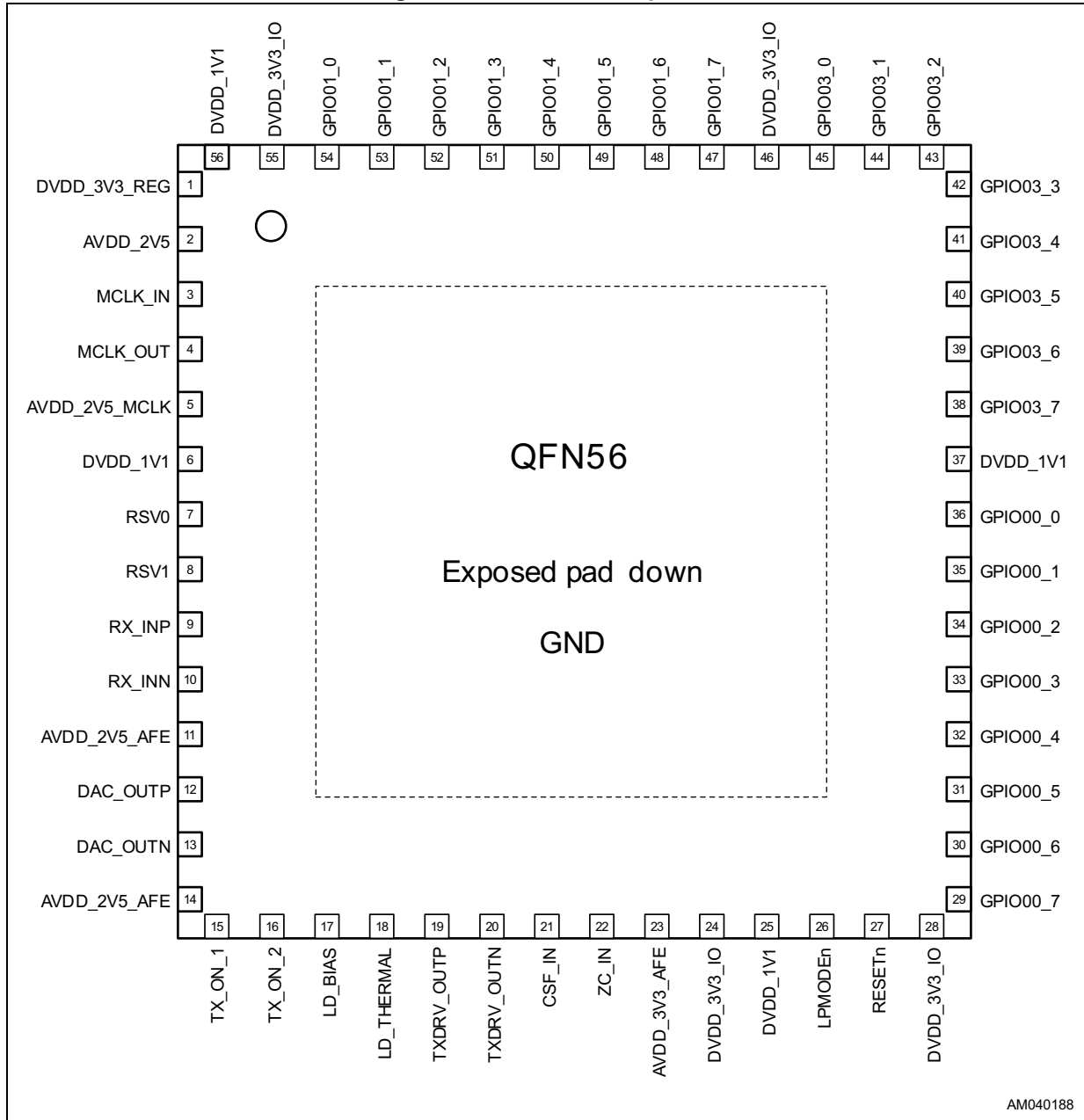


Table 7. Pin description

QFN56 pin	Pin name	Type	RS	Description
1	DVDD_3V3_REG	S	-	3.3 V input for the 2.5 V regulator
2	AVDD_2V5	S	-	2.5 V regulator output
3	MCLK_IN	A	-	25 MHz oscillator input
4	MCLK_OUT	A	-	25 MHz oscillator output
5	AVDD_2V5_MCLK	S	-	FS and oscillator 2.5 V supply
6	DVDD_1V1	S	-	Digital block (FS and oscillator) 1.1 V supply
7	RSV0	-	-	Connect to GND
8	RSV1	-	-	Connect to GND
9	RX_INP	A	I	PGA positive input
10	RX_INN	A	I	PGA negative input
11	AVDD_2V5_AFE	S	-	AFE (PGA) 2.5 V supply
12	DAC_OUTP	A	O	Transmission DAC positive output
13	DAC_OUTN	A	O	Transmission DAC negative output
14	AVDD_2V5_AFE	S	-	AFE (DAC) 2.5 V supply
15	TX_ON_1	A	O	TX enable power amplifier 1
16	TX_ON_2	A	O	TX enable power amplifier 2
17	LD_BIAS	A	O	Line driver bias current
18	LD_THERMAL	A	I	Line driver temperature sense
19	TXDRV_OUTP	A	O	Transmission pre-driver positive output
20	TXDRV_OUTN	A	O	Transmission pre-driver negative output
21	CSF_IN	A	I	Line driver current sense feedback input
22	ZC_IN	A	I	Zero crossing comparator input
23	AVDD_3V3_AFE	S	-	Transmission pre-driver 3.3 V supply
24	DVDD_3V3_IO	S	-	I/O 3.3 V supply
25	DVDD_1V1	S	-	Digital block 1.1 V supply
26	LPMODEn	D	I PU	LOW-POWER mode enable (active low)
27	RESETn	D	I PU	Reset (active low)
28	DVDD_3V3_IO	S	-	I/O 3.3 V supply
29	GPIO00_7	D	I PU	General purpose I/O
30	GPIO00_6	D	I PU	General purpose I/O
31	GPIO00_5	D	I PU	General purpose I/O
32	GPIO00_4	D	I PD	General purpose I/O
33	GPIO00_3	D	I PU	General purpose I/O
34	GPIO00_2	D	I PD	General purpose I/O
35	GPIO00_1	D	I PU	General purpose I/O

Table 7. Pin description (continued)

QFN56 pin	Pin name	Type	RS	Description
36	GPIO00_0	D	I PU	General purpose I/O
37	DVDD_1V1	S	-	Digital block 1.1 V supply
38	GPIO03_7	D	I PU	General purpose I/O (JTAG)
39	GPIO03_6	D	I PU	General purpose I/O (JTAG)
40	GPIO03_5	D	I PU	General purpose I/O (JTAG)
41	GPIO03_4	D	I PD	General purpose I/O (JTAG)
42	GPIO03_3	D	I PU	General purpose I/O (JTAG)
43	GPIO03_2	D	I PD	General purpose I/O (Boot)
44	GPIO03_1	D	I PD	General purpose I/O (Boot)
45	GPIO03_0	D	I PD	General purpose I/O (Boot)
46	DVDD_3V3_IO	S	-	I/O 3.3 V supply
47	GPIO01_7	D(I2C)	I PU	General purpose I/O
48	GPIO01_6	D(I2C)	I PU	General purpose I/O
49	GPIO01_5	D	I PD	General purpose I/O
50	GPIO01_4	D	I PD	General purpose I/O
51	GPIO01_3	D	I PU	General purpose I/O
52	GPIO01_2	D	I PU	General purpose I/O
53	GPIO01_1	D	I PU	General purpose I/O
54	GPIO01_0	D	I PD	General purpose I/O
55	DVDD_3V3_IO	S	-	I/O 3.3 V supply
56	DVDD_1V1	S	-	Digital block 1.1 V supply
57	EXPAD-GND	S	-	Exposed pad - GND

### 3.2 GPIOs multiplexing scheme

In the ST8500 device, peripherals are connected to I/Os through a multiplexer. At a given time, each I/O can be controlled by only one single peripheral. In this way, there is no conflict between peripherals sharing the same I/O pins.

Thanks to a set of configuration registers, the user can select one of the three possible alternate functions for each pin as described in [Table 8](#).

**Table 8. GPIOs multiplexing scheme**

Pin name	Selection: 11	Selection: 00	Selection: 01	Selection: 10
GPIO00_0	Input/output	USART1_RX	SPI2_SCLK	RESERVED
GPIO00_1	Input/output	USART1_TX	SPI2_MOSI	RESERVED
GPIO00_2	Input/output	USART1_RTS	SPI2_SS <sub>n</sub>	RESERVED
GPIO00_3	Input/output	USART1_CTS	SPI2_MISO	RESERVED
GPIO00_4	Input/output	USART0_RX	SPI0_SCLK	RESERVED
GPIO00_5	Input/output	USART0_TX	SPI0_MOSI	RESERVED
GPIO00_6	Input/output	USART0_RTS	SPI0_SS <sub>n</sub>	RESERVED
GPIO00_7	Input/output	USART0_CTS	SPI0_MISO	RESERVED
GPIO01_0	Input/output	SPI1_SCLK	-	RESERVED
GPIO01_1	Input/output	SPI1_MOSI	-	RESERVED
GPIO01_2	Input/output	SPI1_SS <sub>n</sub>	USART0_SCLK	RESERVED
GPIO01_3	Input/output	SPI1_MISO	-	RESERVED
GPIO01_4	Input/output	USART2_RX	I2C0_SMBA	RESERVED
GPIO01_5	Input/output	USART2_TX	USART1_SCLK	RESERVED
GPIO01_6	Input/output	USART2_RTS	I2C0_SDA	RESERVED
GPIO01_7	Input/output	USART2_CTS	I2C0_SCL	RESERVED
GPIO03_0	Input/output	BOOT0	-	RESERVED
GPIO03_1	Input/output	BOOT1	-	RESERVED
GPIO03_2	Input/output	BOOT2	-	RESERVED
GPIO03_3	Input/output	JTAG_TMS/SWIO	-	RESERVED
GPIO03_4	Input/output	JTAG_TCK/SWCLK	-	RESERVED
GPIO03_5	Input/output	JTAG_TDO/SWV	-	RESERVED
GPIO03_6	Input/output	JTAG_TRST <sub>n</sub>	-	RESERVED
GPIO03_7	Input/output	JTAG_TDI	-	RESERVED



# 4 Memory map

Figure 7. ST8500 memory map

0x4001C000	ComSec	PRNG
0x4001B000		TRNG
0x4001A000		AES
0x40019000		CRC
0x40018000		GPT3
0x40017000		GPT2
0x40016000		GPT1
0x40015000		GPT0
0x40014000		I2C0
0x40013000		USART2
0x40012000		USART1
0x40011000		SPI2
0x40010000		SPI1
0x4000A000	Reserved	
0x40009000	Basic	GPIO03
0x40008000		Reserved
0x40007000		GPIO01
0x40006000		GPIO00
0x40005000		OTP
0x40004000		MISC
0x40003000		CRM
0x40002000		WWDG
0x40001000		USART0
0x40000000		SPIO
0x20023000	Reserved	
0x20022FFF	IPC	
0x20022000	SRAM (IPC)	
0x20021FFF	SRAM (IPC)	
0x20020000	Reserved	
0x000A7FFF	SRAM (data)	
0x00090000	SRAM (data)	
0x0008FFFF	SRAM (code and data)	
0x00050000	SRAM (code and data)	
0x0004FFFF	Reserved	
0x00000000	Reserved	

## 5 Electrical characteristics

### 5.1 Absolute maximum ratings

Table 9. Absolute maximum ratings - voltage

Symbol	Parameter	Min.	Max.	Unit
AVDD_2V5	2.5 V internal regulator voltage range	GND - 0.3	3.9	V
AVDD_2V5_AFE	2.5 V PLC AFE supply voltage range	GND - 0.3	3.9	V
AVDD_3V3_AFE	3.3 V PLC AFE supply voltage range	GND - 0.3	3.9	V
DVDD_3V3_IO	3.3 V I/O supply voltage range	GND - 0.3	3.9	V
AVDD_2V5_MCLK	2.5 V MCLK supply voltage range	GND - 0.3	3.9	V
DVDD_1V1	1.1 V digital block supply voltage	GND - 0.3	1.5	V
V(DIG_IN)	Digital pin input voltage range	GND - 0.3	Min. (3.9, DVDD_3V3_IO+0.3)	V
V(MCLK)	25 MHz oscillator pins voltage range	GND - 0.3	Min. (3.9, DVDD_3V3_IO + 0.3)	V
RX_IN	RX_IN pins voltage range	-2.5	5	V
DAC_OUT	DAC output pins voltage range	GND - 0.3	Min. (3.9, AVDD_2.5V_AFE + 0.3)	V
ZC_IN	ZC_IN pin voltage range	-3.3	Min. (3.9, AVDD_3V3_AFE + 0.3)	V
CSF_IN, TX_ON, LD_BIAS, LD_THERMAL, TXDRV_OUT	All other analog pins voltage range	GND - 0.3	Min. (3.9, AVDD_3V3_AFE + 0.3)	V
V(ESD)	Maximum withstanding voltage range test condition: ANSI-ESDA-JEDEC JS-001 "human body model" acceptance criteria: "normal performance"	-2	+2	kV

### 5.2 Thermal characteristics

Table 10. Thermal characteristics

Symbol	Parameter	Conditions	Min.	Max.	Unit
T(J)	Junction temperature	-		125	°C
T(AMB)	Operating ambient temperature	-	-40	105	°C
T(STG)	Storage temperature	-	-50	150	°C

## 5.3 Operating conditions

T(AMB) = -40 to +105 °C, T(J) < 125 °C unless otherwise specified.

### Power supply characteristics

**Table 11. Analog supply characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
V(AVDD_2V5)	2.5 V regulator output	-	2.3	2.5	2.75	V
V(DVDD_3V3_REG)	2.5 V regulator input voltage	-	3	3.3	3.6	V
I(DVDD_3V3_REG)	2.5 V regulator quiescent current	-	-	-	1.5	mA
V(AVDD_2V5_AFE)_TH	2.5 V PLC AFE supply voltage turn-on threshold	-	-	2.1	2.25	V
V(AVDD_2V5_AFE)_TL	2.5 V PLC AFE supply voltage turn-off threshold	-	1.8	1.9	-	V
V(AVDD_2V5_AFE)_HYST	2.5 V PLC AFE supply voltage hysteresis	-	-	200	-	mV
I(AVDD_2V5_AFE)_RX	2.5 V PLC AFE supply current in Rx mode	-	-	6.5	7.5	mA
I(AVDD_2V5_AFE)_TX	2.5 V PLC AFE (PGA and DAC) supply current in Tx mode	DAC full scale current = 10 mA Fclk: 20 MHz	-	10	-	mA
I(AVDD_3V3_AFE)_RX	3.3 V PLC AFE supply current in Rx mode	-	-	0.03	0.1	mA
I(AVDD_3V3_AFE)_TX	3.3 V PLC AFE supply current in Tx mode	TXDRV_OUT pins with no load	-	3	5	mA
V(DVDD_3V3_IO)	Digital I/O supply voltage	-	3.0	3.3	3.6	V
V(DVDD_3V3_IO)_TH	Digital I/O supply voltage turn-on threshold	-	-	2.7	2.85	V
V(DVDD_3V3_IO)_TL	Digital I/O supply voltage turn-off threshold	-	2.4	2.5	-	V
V(DVDD_3V3_IO)_HYST	Digital I/O supply voltage hysteresis	-	-	200	-	mV
V(DVDD_1V1)	1.1 digital block supply	-	1.05	1.1	1.21	V
V(DVDD_1V1)_TH	1.1 supply voltage turn-on threshold	-	-	0.93	1.03	V
V(DVDD_1V1)_TL	1.1 supply voltage turn-off threshold	-	0.65	0.73	-	V
V(DVDD_1V1)_HYST	1.1 supply voltage hysteresis	-	-	200	-	mV

**Table 12. Digital supply characteristics - RTE**

Symbol	Parameter	Conditions <sup>(1)</sup>	Min.	Typ.	Max.	Unit
I(DVDD_1V1)	1.1 V digital supply current	RTE frequency = 50 MHz	-	3	-	mA
I(DVDD_1V1)	1.1 V digital supply current	RTE frequency = 120 MHz	-	36	-	mA
I(DVDD_1V1)	1.1 V digital supply current	RTE frequency = 250 MHz	-	60	-	mA
I(DVDD_1V1)	1.1 V digital supply current	RTE frequency = 400 MHz	-	128	-	mA

1. The tests are performed with the following enabled blocks: 1 x GPT, 1 x SPI, 1 x USART, IPC, AES, TRNG, ROSC. Cortex™ frequency equals to 100 MHz. The value is calculated by measuring the difference in the supply current with and without RTE enabled and running.

**Table 13. Digital supply characteristics - Cortex™-M4**

Symbol	Parameter	Conditions <sup>(1)</sup>	Min.	Typ.	Max.	Unit
I(DVDD_1V1)	1.1 V digital supply current	Cortex™ frequency = 50 MHz	-	20	-	mA
I(DVDD_1V1)	1.1 V digital supply current	Cortex™ frequency = 100 MHz	-	32	-	mA
I(DVDD_1V1)	1.1 V digital supply current	Cortex™ frequency = 200 MHz	-	38	-	mA

1. The tests are performed with the following enabled blocks: 1 x GPT, 1 x SPI, 1 x USART, IPC, AES, TRNG, ROSC.

**Table 14. Digital supply characteristics - low power modes**

Symbol	Parameter	Conditions <sup>(1)</sup>	Min.	Typ.	Max.	Unit
I(DVDD_1V1)	1.1 V digital supply current	Cortex™ in SLOW, clock fed by 25 MHz XOSC	-	9	-	mA
I(DVDD_1V1)	1.1 V digital supply current	Cortex™ in DOZE or LOW-POWER, clock fed by ROSC	-	7.5	-	mA
I(DVDD_1V1)	1.1 V digital supply current	Cortex™ in LOW-POWER mode, clock fed by ROSC, AFE disabled	-	7.5	-	mA
I(DVDD_1V1)	1.1 V digital supply current	Cortex™ in LOW-POWER mode, clock fed by ROSC, external clock sources disabled	-	7.5	-	mA
I(DVDD_1V1)	1.1 V digital supply current	Cortex™ in LOW-POWER mode, clock fed by ROSC, all digital blocks disabled but Cortex™	-	7.5	-	mA

1. The tests are performed with the following enabled blocks: 1 x GPT, 1 x SPI, 1 x USART, IPC, AES, TRNG, ROSC.

**Table 15. Supply characteristics - oscillator and clock**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I(DVDD_2V5_MCLK)	FS current consumption from 2.5 V power supply	Master clock - 25 MHz	-	1.8	2.5	mA
I(DVDD_1V1)	FS current consumption from 1.1 V power supply	Master clock - 25 MHz	-	3.5	5	mA
I(DVDD_2V5_MCLK)	XOSC current consumption from 2.5 V power supply	Master clock - 25 MHz	-	0.5	1	mA
I(DVDD_1V1)	ROSC current consumption from 1V1 power supply	Master clock - 25 MHz	-	0.15	1.5	mA

Table 16. Digital supply characteristics - I/O

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I(DVDD_3V3_IO)	3.3 V digital supply current consumption	8 GPIO toggling at 0.5 MHz with $C_{ext} \cong 50$ pF see <sup>(1)</sup>	-	2.8	6	mA
I(DVDD_3V3_IO)	3.3 V digital supply current consumption	8 GPIO toggling at 1 MHz with $C_{ext} \cong 50$ pF see <sup>(1)</sup>	-	5.5	11	mA
I(DVDD_3V3_IO)	3.3 V digital supply current consumption	8 GPIO toggling at 8 MHz with $C_{ext} \cong 50$ pF see <sup>(1)</sup>	-	33	76	mA

1. The tests are performed with the following enabled blocks: 1 x GPT, 1 x SPI, 1 x USART, IPC, AES, TRNG, ROSC. Cortex™ frequency equals to 100 MHz.

Table 17. Digital supply characteristics - OTP

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I(DVDD_2V5)	2.5 V digital supply current consumption <sup>(1)</sup>	OTP static consumption	-	20	-	nA
I(DVDD_1V1)	1.1 V digital supply current consumption <sup>(1)</sup>	OTP read operation	-	-	0.4	mA

1. Guaranteed by design, not tested in production.

## 5.4 PLC analog front-end (AFE) characteristics

### 5.4.1 Transmission path characteristics

Table 18. DAC and pre-driver characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I(DAC_OUT) FS	DAC output full-scale current	Tx mode, current measured on both outputs	-	10	-	mA
V(DAC_OUT)	Tx mode, differential	Rload = 50 Ω ± 1%, FS = 10 mA	-	1	-	Vpp
V(TX_OUT) BIAS	Transmitter output bias voltage	Rx mode	-	AVDD_3V3_AFE/2	-	V
-	Pre-driver load impedance <sup>(1)</sup>	-	1	-	-	kΩ
V(TX_OUT) HD2	Transmitter output 2 <sup>nd</sup> harmonic distortion - see <sup>(2)</sup>	V(TX_OUT) = 4.6 V pk-pk, no load, Fout = 100 KHz, single-ended T(AMB) = 25 °C	-	-66	-	dBc
V(TX_OUT) HD3	Transmitter output 3 <sup>rd</sup> harmonic distortion see <sup>(2)</sup>		-	-75	-	dBc
V(TX_OUT) THD	Transmitter output total harmonic distortion see <sup>(2)</sup>		-	-65	-	dB
V(TX_OUT) HD2	Transmitter output 2 <sup>nd</sup> harmonic distortion	V(TX_OUT) = 4.6 V pk-pk, no load, Fout = 100 KHz, differential T(AMB) = 25 °C	-	-69	-	dBc
V(TX_OUT) HD3	Transmitter output 3 <sup>rd</sup> harmonic distortion		-	-75	-	dBc
V(TX_OUT) THD	Transmitter output total harmonic distortion		-	-67	-60	dB
V(TX_OUT) HD2	Transmitter output 2 <sup>nd</sup> harmonic distortion - see <sup>(2)</sup>	V(TX_OUT) = 4.6 V pk-pk, no load, Fout = 500 KHz, single-ended T(AMB) = 25 °C	-	-61	-	dBc
V(TX_OUT) HD3	Transmitter output 3 <sup>rd</sup> harmonic distortion see <sup>(2)</sup>		-	-73	-	dBc
V(TX_OUT) THD	Transmitter output total harmonic distortion see <sup>(2)</sup>		-	-60	-	dB
V(TX_OUT) HD2	Transmitter output 2 <sup>nd</sup> harmonic distortion	V(TX_OUT) = 4.6 V pk-pk, no load, Fout = 500 KHz, differential T(AMB) = 25 °C	-	-72	-	dBc
V(TX_OUT) HD3	Transmitter output 3 <sup>rd</sup> harmonic distortion		-	-75	-	dBc
V(TX_OUT) THD	Transmitter output total harmonic distortion		-	-69	-60	dB

1. Guaranteed by design, not tested in production.

2. Based on characterization, not tested in production.

## 5.4.2 Reception path characteristics

**Table 19. Receiver input referred noise**

Symbol	Parameter <sup>(1)</sup>	Conditions	Min.	Typ.	Max.	Unit
V(RX_INP - RX_INN)	Receiver input referred noise	CENELEC-A (35 kHz to 95 kHz)	-	17	-	dB $\mu$ V
		CENELEC -B (95 kHz to 125 kHz)	-	14	-	dB $\mu$ V
		CENELEC -C (125 kHz to 140 kHz)	-	11	-	dB $\mu$ V
		CENELEC -D (140 kHz to 148 kHz)	-	8	-	dB $\mu$ V
		ARIB STD-T84 (35 kHz to 400 kHz)	-	24	-	dB $\mu$ V
		FCC-LOW (35 kHz to 125 kHz)	-	19	-	dB $\mu$ V
		G3-FCC (150 kHz to 490 kHz)	-	24	-	dB $\mu$ V

1. Guaranteed by design, not tested in production.

**Table 20. PGA characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
V(RX_INP), V(RX_INN)	Receiver input maximum voltage	Single-ended mode	-	7.5	-	V p-p
V(RX_INP -RX_INN)	Receiver input maximum voltage	Differential mode	-	15	-	V p-p
V(RX_INP), V(RX_INN)	Receiver input bias voltage	-	-	(AVDD_2V5 AFE) * 0.475	-	V
Z(RX_INP), Z(RX_INN)	Receiver input impedance	Single-ended	-	5	-	k $\Omega$
GPGA	PLC PGA minimum gain	-	-	-18	-	dB
	PLC PGA maximum gain	-	-	54	-	dB
GPGA Step	PLC PGA gain step	-	-	3	-	dB

**Table 21. ADC characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
ADC input range	-	Differential mode	-	1.8	-	V p-p
Resolution	-	-	-	11	-	bit

### 5.4.3 Zero crossing comparator characteristics

Table 22. Zero crossing characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
V(ZC_IN)MAX	Zero crossing Detection input Voltage range	-	-3.3	-	AVDD_3V3_AFE	V
V(ZC_IN)TL	Zero crossing Detection input Low threshold	-	-	-6	-	mV
V(ZC_IN)TH	Zero crossing Detection input High threshold	-	-	+6	-	mV
ZC_INd.c.	Zero crossing Input duty cycle	-	-	50	-	%

### 5.5 Other characteristics

Table 23. I/O characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I(I/O)	Output current sunk by any I/Os and control pin	-	-	-	8	mA
	Output current sourced by any I/Os and control pin	-	-	-	8	mA
R_PU	Pull-up resistor	No load	38	50	68	kΩ
R_PD	Pull-down resistor	No load	38	50	68	kΩ
VIH	High level input voltage	-	DVDD_3V3_IO * 0.7	-	-	V
VIL	Low level input voltage	-	-	-	DVDD_3V3_IO * 0.3	V
VOH	High level output voltage	8 mA sourced current	2.8	-	-	V
VOL	Low level output voltage	8 mA sunk current	-	-	0.4	V

Table 24. 25 MHz oscillator characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
f(MCLK)	Crystal oscillator frequency	-	-	25	-	MHz
C0	External quartz crystal shunt capacitance	-	-	-	2.6	pF
ESR	External quartz crystal ESR value	See <sup>(1)</sup>	-	-	20	Ω
CL	MCLK_IN, MCLK_OUT load capacitance	See <sup>(1)</sup>	-	18	-	pF

1. Guaranteed by design, not tested in production.



Table 25. Low-power RC oscillator (ROSC) characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
f(ICLK)	Internal RC oscillator frequency	-	3.1	4.2	5.5	MHz

## 6 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK® is an ST trademark.

### 6.1 QFN56 (7 x 7 x 1 mm) package information

Figure 8. QFN56 (7 x 7 x 1 mm) package outline

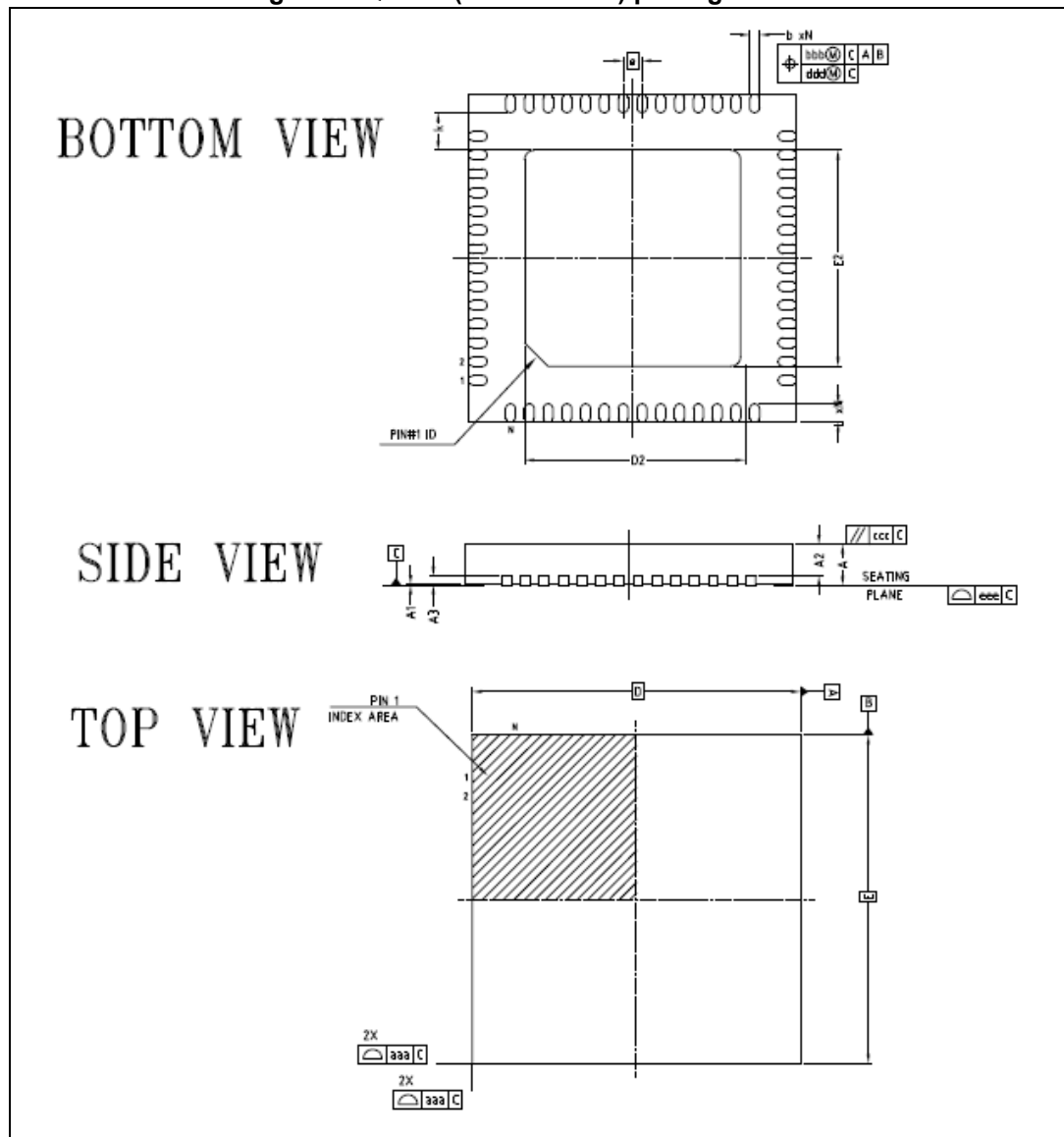


Table 26. QFN56 (7 x 7 x 1 mm) package mechanical data

Symbol	Dimension (millimeters)		
	Min.	Typ.	Max.
A	0.80	0.85	0.90
A1	0	-	0.05
A2	-	0.65	-
A3	-	0.20	-
b	0.16	0.21	0.26
D	-	7.00	-
D2	4.50	4.60	4.70
e	-	0.40	-
E	-	7.00	-
E2	4.50	4.60	4.70
L	0.35	0.40	0.45
k	0.70	-	-
N	-	56	-

Table 27. QFN56 (7 x 7 x 1 mm) package tolerance of form and position

Symbol	Millimeters
aaa	0.10
bbb	0.07
ccc	0.10
ddd	0.05
eee	0.08

## 7 Revision history

**Table 28. Document revision history**

Date	Revision	Changes
25-Oct-2017	1	Initial release.
08-Nov-2017	2	Minor updates in Features and Description.
19-Jun-2018	3	Updated <a href="#">Table 1 on page 1</a> (added ST8500TR and Tray).

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